

CURRENT DATE: 2-APRIL-2014

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TE CONNECTIVITY

PRODUCT CHANGE NOTIFICATION

CUSTOMER: HEILIND ELECTRONICS

PRODUCT CHANGE NOTIFICATION NO: E-13-019830

LOCATION: WILMINGTON

PCN DATE: 01-APR-14

CUSTOMER NO: 167811

AGREEMENT NO:

TE CONNECTIVITY ENTITY: RMP (1082) - U.S. Operations on SAP

We would like to inform you about the following change(s) to the listed TE Connectivity Product. In case of any further questions about this change(s), please contact your TE Connectivity Sales Engineer. Affected part, drawing and/or specification numbers are listed on the attached sheet(s).

GENERAL PRODUCT DESCRIPTION:

Micro-MaTch, Female-On-Board, SMD connectors (188275 & 33806)

DESCRIPTION OF CHANGE:

Packaging blister or pocket tape material changed from PET clear to PS clear.

REASON FOR CHANGE:

Product Improvement. Packaging improvement, Blister tape to withstand higher temperatures up to 90 deg Celsius /60 percent RH.

ESTIMATE DATE:

LAST ORDER DATE:

(OBSOLETE PARTS ONLY)

LAST SHIP DATE:

(OBSOLETE PARTS ONLY)

FIRST DATE TO SHIP CHANGED PARTS:

01-JUN-2014

(CHANGED PARTS ONLY)

LAST DATE FOR MIXED

SHIPMENTS: 31-DEC-2014

(CHANGED PARTS ONLY)

CURRENT DATE: 2-APRIL-2014

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PARTS BEING MODIFIED

CUSTOMER PART NBR

7-188275-4